

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT																		
NATURE OF CONVEYANCE:	ASSIGNMENT																		
CONVEYING PARTY DATA <table border="1" style="width: 100%; border-collapse: collapse; margin-top: 10px;"> <thead> <tr> <th style="width: 70%;">Name</th> <th style="width: 30%;">Execution Date</th> </tr> </thead> <tbody> <tr><td>Jong-Woo Ha</td><td>10/01/2007</td></tr> <tr><td>Koo Hong Lee</td><td>10/01/2007</td></tr> <tr><td>Soo Won Lee</td><td>10/01/2007</td></tr> <tr><td>JuHyun Park</td><td>10/01/2007</td></tr> <tr><td>Zigmund Ramirez Camacho</td><td>09/28/2007</td></tr> <tr><td>Jeffrey D. Punzalan</td><td>09/28/2007</td></tr> <tr><td>Lionel Chien Hui Tay</td><td>09/28/2007</td></tr> <tr><td>Jairus Legaspi Pisigan</td><td>09/28/2007</td></tr> </tbody> </table>		Name	Execution Date	Jong-Woo Ha	10/01/2007	Koo Hong Lee	10/01/2007	Soo Won Lee	10/01/2007	JuHyun Park	10/01/2007	Zigmund Ramirez Camacho	09/28/2007	Jeffrey D. Punzalan	09/28/2007	Lionel Chien Hui Tay	09/28/2007	Jairus Legaspi Pisigan	09/28/2007
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RECEIVING PARTY DATA <table border="1" style="width: 100%; border-collapse: collapse; margin-top: 10px;"> <tr><td style="width: 20%;">Name:</td><td>STATS ChipPAC Ltd.</td></tr> <tr><td>Street Address:</td><td>5 Yishun Street 23</td></tr> <tr><td>City:</td><td>Singapore</td></tr> <tr><td>State/Country:</td><td>SINGAPORE</td></tr> <tr><td>Postal Code:</td><td>768442</td></tr> </table>		Name:	STATS ChipPAC Ltd.	Street Address:	5 Yishun Street 23	City:	Singapore	State/Country:	SINGAPORE	Postal Code:	768442								
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CORRESPONDENCE DATA <p style="margin-top: 10px;">Fax Number: (408)738-0881 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: (408) 738-0592 Email: efiling@ishimarulaw.com Correspondent Name: Mikio Ishimaru Address Line 1: Ishimaru & Zahrt LLP Address Line 2: 333 W. El Camino Real, Suite # 330 Address Line 4: Sunnyvale, CALIFORNIA 94087</p>																			

CH \$40.00 11864826

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PATENT
REEL: 019923 FRAME: 0210

ATTORNEY DOCKET NUMBER:	27-394
NAME OF SUBMITTER:	Mikio Ishimaru
<p>Total Attachments: 5</p> <p>source=27-394_ASSIGNMENT#page1.tif</p> <p>source=27-394_ASSIGNMENT#page2.tif</p> <p>source=27-394_ASSIGNMENT#page3.tif</p> <p>source=27-394_ASSIGNMENT#page4.tif</p> <p>source=27-394_ASSIGNMENT#page5.tif</p>	

ASSIGNMENT

WHEREAS, the undersigned (hereinafter termed Assignor(s)) has/have invented certain new and useful improvements in

INTEGRATED CIRCUIT PACKAGING SYSTEM WITH BASE STRUCTURE DEVICE

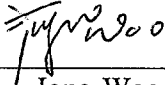
for which a United States patent application has been executed on or before the date of this assignment;

WHEREAS, STATS ChipPAC Ltd., a Corporation of the Republic of Singapore, having a place of business at 5 Yishun Street 23, Singapore 768442 (hereinafter termed Assignee), is desirous of acquiring the entire right, title and interest in and to said application and said invention and improvements thereon, and in and to Letters Patents thereon when granted in the United States and foreign countries;

NOW, THEREFORE, for good and valuable consideration received by said Assignor(s) from said Assignee, the receipt of which is hereby acknowledged by said Assignor(s):

1. Said Assignor(s) does hereby sell, assign, transfer and convey unto said Assignee, the entire right, title and interest in and to said application and said invention and in and to any and all improvements on said invention and in and to any and all improvements on said invention heretofore or hereafter made or acquired by said Assignor(s); and in and to any and all Letters Patent on said invention and/or said improvements that may be granted in the United States or any foreign country, including each and every Letters Patent granted on any application which is a division, continuation, substitution, renewal, or continuation-in-part of any said application, and in and to each and every reissue or extension of said Letters Patent.
2. Said Assignor(s) hereby covenants and agrees to cooperate with said Assignee where said Assignee may enjoy to the fullest extent the right, title and interest herein conveyed. Such cooperation shall include (a) prompt execution of all papers (prepared at the expense of Assignee) which are deemed necessary or desirable by Assignee to perfect in it the right, title and interest herein conveyed, (b) prompt execution of all petitions, oaths, specifications or other papers (prepared at the expense of Assignee) which are deemed necessary or desirable by assignee for prosecuting said application, for filing and prosecuting divisional, continuation, substitution, renewal, continuation-in-part, or additional applications in the United States and/or foreign countries covering said invention and/or said improvements, for filing and prosecuting applications for reissuance of letters patent included herein, or for interference proceedings involving said invention and/or said improvements and (c) prompt assistance and cooperation in the prosecution of interference proceedings involving said invention and/or said improvements and in the adjudication of said Letters Patent, particularly by the disclosure of facts and the production of evidence relating to said invention and/or said improvements, provided the expenses which may be incurred by said Assignor(s) in lending such assistance and cooperation shall be paid by the Assignee.
3. The terms, covenants and conditions of this assignment shall inure to the benefit of said Assignee, its successors, assigns and/or other legal representatives and shall be binding upon said Assignor(s), his/her heirs, legal representatives and assigns.
4. Said Assignor(s) hereby warrants and represents that he/she has not entered into any assignment, contract or understanding in conflict herewith.

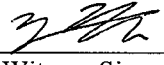
IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below.




Jong-Woo Ha

Oct. 01, 2007

Date



Witness Signature



Witness Signature

Jo Hyun BAE

Print Witness Name

Mee Seob SHIM.

Print Witness Name

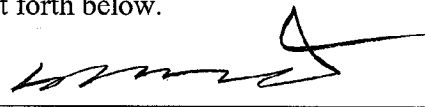
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Date

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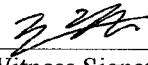
IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below.




Koo Hong Lee

Oct. 01 '07

Date



Witness Signature



Witness Signature

Jo Hyun BAE

Print Witness Name

Mee Seob SHIM

Print Witness Name

Oct 01 '07

Date

Oct. 01 '07

Date

IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below.




Soo Won Lee

Oct. 01, 2007

Date



Witness Signature



Witness Signature

Jo Hyun BAE

Print Witness Name

Mee Seob SHIM

Print Witness Name



Oct 01 '07

Date

Oct. 01 '07

Date

Date Oct. 01 '07

	
Jeffrey D. Punzalan	Date
Witness Signature	Witness Signature
Print Witness Name	Print Witness Name
Date	Date

IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below.

<u>JuHyun Park</u>	<u> </u>
Date	
<u> </u>	<u> </u>
Witness Signature	Witness Signature
<u> </u>	<u> </u>
Print Witness Name	Print Witness Name
<u> </u>	<u> </u>
Date	Date

IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below.

Zigmond Ramirez Camacho
Zigmond Ramirez Camacho

28 Sept, 2007
Date

TRASPOTO ARNEL S.
Witness Signature
Print Witness Name

ADVINCULA ABELARDO JR H.
Witness Signature
Print Witness Name

28 SEPT. 2007
Date

28 SEPT 2007
Date

IN WITNESS WHEREOF, the said Assignor has executed and delivered this instrument on the date set forth below.

Jeffrey D. Punzalan
Jeffrey D. Punzalan

28 Sept 2007
Date


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Lionel Chien Hui Tay



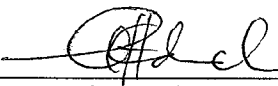
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TRASPORTO ARNEL S.

Print Witness Name
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28 Sept. 2007

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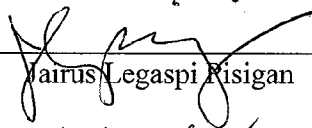


Witness Signature
ADVINCULA ABELARDO JR H.

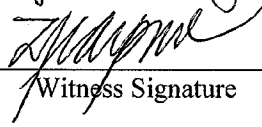
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Jairus Legaspi Pisigan



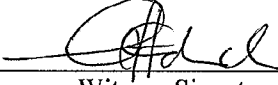
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TRASPORTO ARNEL S.

Print Witness Name
28 SEPT 2007

Date

28 Sept. 2007

Date



Witness Signature
ADVINCULA ABELARDO JR H.

Print Witness Name
28 SEPT 2007

Date